

WFM5200
Waveform Monitor
Service Manual



WFM5200 Waveform Monitor Service Manual

#### Warning

The servicing instructions are for use by qualified personnel only. To avoid personal injury, do not perform any servicing unless you are qualified to do so. Refer to all safety summaries prior to performing service.

www.tektronix.com

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For product information, sales, service, and technical support:

- In North America, call 1-800-833-9200.
- Worldwide, visit www.tektronix.com to find contacts in your area.

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# **General Safety Summary**

Review the following safety precautions to avoid injury and prevent damage to this product or any products connected to it.

To avoid potential hazards, use this product only as specified.

Only qualified personnel should perform service procedures.

While using this product, you may need to access other parts of a larger system. Read the safety sections of the other component manuals for warnings and cautions related to operating the system.

# To Avoid Fire or Personal Injury

**Use proper power cord.** Use only the power cord specified for this product and certified for the country of use.

**Ground the product.** This product is grounded through the grounding conductor of the power cord. To avoid electric shock, the grounding conductor must be connected to earth ground. Before making connections to the input or output terminals of the product, ensure that the product is properly grounded.

**Observe all terminal ratings.** To avoid fire or shock hazard, observe all ratings and markings on the product. Consult the product manual for further ratings information before making connections to the product.

Do not apply a potential to any terminal, including the common terminal, that exceeds the maximum rating of that terminal.

**Power disconnect.** The power cord disconnects the product from the power source. Do not block the power cord; it must remain accessible to the user at all times.

**Do not operate without covers.** Do not operate this product with covers or panels removed.

**Do not operate with suspected failures.** If you suspect that there is damage to this product, have it inspected by qualified service personnel.

**Avoid exposed circuitry.** Do not touch exposed connections and components when power is present.

**Use proper AC adapter.** Use only the AC adapter specified for this product.

Do not operate in wet/damp conditions.

Do not operate in an explosive atmosphere.

Keep product surfaces clean and dry.

**Provide proper ventilation.** Refer to the manual's installation instructions for details on installing the product so it has proper ventilation.

### **Terms in This Manual**

These terms may appear in this manual:



**WARNING.** Warning statements identify conditions or practices that could result in injury or loss of life.



**CAUTION.** Caution statements identify conditions or practices that could result in damage to this product or other property.

# Symbols and Terms on the Product

These terms may appear on the product:

- DANGER indicates an injury hazard immediately accessible as you read the marking.
- WARNING indicates an injury hazard not immediately accessible as you read the marking.
- CAUTION indicates a hazard to property including the product.

The following symbol(s) may appear on the product:





CAUTION Refer to Manual

# **Service Safety Summary**

Only qualified personnel should perform service procedures. Read this *Service Safety Summary* and the *General Safety Summary* before performing any service procedures.

**Do Not Service Alone.** Do not perform internal service or adjustments of this product unless another person capable of rendering first aid and resuscitation is present.

**Disconnect Power.** To avoid electric shock, switch off the instrument power, then disconnect the power cord from the mains power.

**Use Care When Servicing With Power On.** Dangerous voltages or currents may exist in this product. Disconnect power, remove battery (if applicable), and disconnect test leads before removing protective panels, soldering, or replacing components.

To avoid electric shock, do not touch exposed connections.

# **Preface**

This manual supports servicing to the module level of the WFM5200 Waveform Monitor, which processes video signals for display on an internal XGA LCD. The instrument is used as a monitor in broadcasting, production and post-production environments.

This manual explains how to troubleshoot and service the instrument to the module level. The manual is divided into the following sections:

- *Introduction* provides a general product description and tells where to find product installation information.
- *Theory of Operation* provides descriptions of the modules of the instrument.
- Adjustment Procedures details the adjustments that to perform if the instrument is out of specification.
- Maintenance tells you how to troubleshoot the product to the module level and how to handle the modules.
- Replaceable Parts illustrates the replaceable modules and mechanical parts, and provides replacement part numbers.

## **Manual Conventions**

The following terms and conventions are used throughout this manual:

The term "instrument" is used interchangeably with the more formal term "WFM5200 Waveform Monitor."

## **Related Manuals**

This manual assumes you have access to the following manuals when servicing this product. These manuals are available on the Product Documentation CD that shipped with the product and can also be downloaded from www.tektronix.com/manuals.

Table i: Related documentation

Item	Purpose	Location
WFM5200 Waveform Monitor User	Operation instructions and explanation	Product Documentation CD
Manual	of features	www.tektronix.com/manuals
WFM5200 Waveform Monitor Installation	Basic installation and safety information	Printed manual
and Safety Instructions, English,		Product Documentation CD
Japanese, Simplified Chinese		www.tektronix.com/manuals
WFM5200 Online Help	In-depth operation and UI help	In the instrument: press the HELP button on the front panel

## Table i: Related documentation (cont.)

Item	Purpose	Location
WFM5200 Waveform Monitor Specifications and Performance Verification	Procedure for checking performance and list of specifications	Product Documentation CD www.tektronix.com/manuals
WFM and WVR Series Management Information Database (MIB)	Programmers command reference for controlling the waveform monitor	Product Documentation CD www.tektronix.com/manuals

# Introduction

The WFM5200 Waveform Monitor provides a powerful monitoring solution for broadcast, production, and post-production environments.

# **Service Strategy**

These products are repaired to the module level at selected Tektronix service centers. Repair includes functional verification of the product. Component level repair by the customer is not supported.

# **Specifications**

The specifications for this product are found in the *WFM5200 Waveform Monitor Specifications and Performance Verification Technical Reference* located on the Product Documentation CD which ships with the product and is published on the Tektronix Web site. (See page vii, *Related Manuals*.)

## **Performance Verification**

The Performance Verification procedures for this product are found in the WFM5200 Waveform Monitor Specifications and Performance Verification Technical Reference located on the Product Documentation CD which ships with the product and is published on the Tektronix Web site. (See page vii, Related Manuals.)

## **Options and Accessories**

The lists of options and accessories for this product are found in the *WFM5200 Waveform Monitor User Manual* located on the Product Documentation CD that ships with the product and is published on the Tektronix Web site. (See page vii, *Related Manuals*.)

## **Configurations**

The base instrument has no hardware upgrade options. Software options are available to add capabilities such as audio and advanced gamut monitoring. For a complete list of options, refer to the *WFM5200 Waveform Monitor User Manual*.

## **Hardware Installation**

The waveform monitor is shipped in a one-piece, unpainted, bathtub shaped, EMI shell. It can be used as-is or installed into a hard carry case, soft carry case (requires hard carry case), or rack mount cabinet. For instructions about installation into a rack mount or cabinet, refer to the WFM5200 Waveform Monitors System Integration Technical Reference or the rack adapter instructions included with your Tektronix rack mount kit.

# **Product Upgrade**

Software upgrades are available for all products as free software downloads from the Tektronix Web site. The *WFM5200 Waveform Monitor User Manual* includes instructions for updating product software. If you would like to purchase additional features and capabilities for your instrument, contact Tektronix for more information on purchasable options. For a complete list of options, refer to the *WFM5200 Waveform Monitor User Manual*.

## **Operating Information**

For operating instructions, refer to the *WFM5200 Waveform Monitor User Manual*. For more detailed reference information, refer to the instrument Online help. (Press the **Help** button on the instrument front panel and then use the **General** knob, up/down arrow keys, and **SEL** button to navigate through the topics.)

#### Power-On Procedure

- 1. Connect the supplied power cord to the external AC adapter, and connect its XLR output connector to the instrument.
- **2.** Press the power button on the instrument front-panel and the instrument will turn on.
- **3.** Wait for the system to complete its power-on self-tests.

#### **Power-Off Procedure**

- 1. Press the power button on the instrument front-panel to turn the instrument off.
- **2.** To remove power completely, disconnect the power cord from the AC adapter.

**NOTE.** The power button on the front-panel does not disconnect mains power. Only the power cord at the AC adapter can disconnect mains power.

# **Theory of Operation**

The WFM5200 is a modular waveform monitor. Each instrument includes extensive standard capabilities, which can be augmented by adding various options.

This instrument uses an internal DVI-I monitor for the display, and has an output to drive an external monitor with the same display. It also has outputs to drive a serial digital picture monitor.

This theory of operation is based on the High-level Block diagram. (See Figure 1.)

The block diagram reflects the physical arrangement of circuit boards with the CPU board at the bottom, the SDI board in the center, and the FPGA board at the top. Connectors to the External Reference and front panel boards are shown.

The primary functions on the CPU board are:

- Control processor kernel
- front panel interface
- Display backlight
- Fan controller
- Headphones output and control
- USB and network connections
- Various secondary power supplies

The primary functions on the SDI board are:

- SDI Input signal conditioning
- Input power conditioning and control

The primary functions on the FPGA board are:

- Serial digital input processing
- Waveform and picture processing for display
- DVI output
- Reference input data processing
- SDI output generation

**REF IO BOARD** External Reference Loop-Through MUX SLICER **Ground Closure** Interface (incl. LTC) 15 PINS 1.0V 0.9V -5V DISPLAY DDR2 DDR2 DDR2 SD/HD/3G OUT DDR2 DDR2 Audio VCXO J15 Clocks SDI DISPLAY DATA Ref, LCD, JTAG DSY DVI-D CPU BUS - П ⟨лтаĞ⟩ FPGA **DVI-I OUT FPGA** √JAG QDR2 **BOARD** SDI (4x) DSP J14 QDRII Bd-Bd IO SD/HD/3G IN 1A EQ SD/HD/3G IN 1B EQ SDI 10 **BOARD** SD/HD/3G IN 2A EQ EQ SD/HD/3G IN 2B 12VDC IN (10V-17V) 3.3V +5V 0 J11 DEBUG Front J2 Debug & JTAG Front panel intf panel board CPU PLD Bd-Bd buffers Bd-Bd IO J9 System reset Backlight driver Back-Light NVRAM / RTC CPU BUS CPU BUS 440EP Audio J13 Headphones Microprocessor RS232 & A/D USB USB J6 Dram phy RJ45 Fan ETHERNET **CPU BOARD** Clocks **ETHERNET** Fan pwr J8 Fan 1.5V 1.8V 2.5V -5V 0550-001

Power Distribution is not shown in the block diagram but is covered at the end of this section.

Figure 1: Instrument block diagram

### **CPU Board**

# Serial Digital Input Processing

The serial digital circuitry receives the SDI input streams from the SDI board after they have been equalized. The SDI input streams are passed to the DSP FPGAs where they undergo measurement and raster processing. The signal information is then passed to the DSY FPGA for picture processing, recursion, and display combining. The result is shown on the LCD display, and also provided to the external DVI-I connector.

### **Reference Input**

The reference input is a passive loopthrough, which is AC coupled and buffered. The reference signal is applied to a sync separator whose output is supplied to the DSP FPGA, where the timing information is derived. The reference signal is also digitized for display as a waveform.

# **Digital Waveform Processing Engine**

The data streams from the SDI video inputs are applied to the waveform processing FPGA. This block deformats, up-samples, interpolates, and otherwise processes the data to generate the signals needed to create the displays.

### **Rasterizing Engine**

The rasterizer engine resides in the same DSP FPGA as the waveform processing engine. This block builds up the variable intensity images in the fast static RAM. For each pixel of the display, the rasterizer engine increments the intensity of that pixel every time the waveform hits its coordinates. As a result, the waveform areas that are hit more frequently are brighter. For any given frame, the intensity map is built up in one memory chip and read out of the other. The functions swap on the next field.

## Recursion and Picture Processing Engine

The output of the rasterizing engine feeds the picture and recursive processing engine in the second large FPGA. This engine adds the previous frame to the present frame to reduce flicker and improve brightness. It also converts the picture and waveform signals from various input frames rates to a 60 Hz frame rate in order to work with the DVI-I monitor. The picture and waveform data are then combined with the graphics and audio bar information from the control processor. The result is presented on the LCD display, and sent through the DVI connector to the external monitor.

## CPU Board Control Processor

The control processor is in charge of all the operational modes in the instrument. It communicates with the FPGAs on the FPGA board through a parallel peripheral bus and communicates with the front panel, and controls most other internal devices though either the SPI or the I<sup>2</sup>C bus.

The control processor interfaces to the Ethernet through a dual rate connection. This allows the network connection to run at 10 or 100 MBps.

#### LTC

LTC inputs come from the remote connector. The LTC signal is applied to an A/D converter and then input to the waveform processing FPGA, which decodes the time code information.

**NOTE**. The FPGAs decode VITC signals digitally.

## **Front Panel**

The front panel contains a small processor which communicates with the control processor through SPI signaling. Reprogramming can be done through the SPI if the front panel processor flash code must be updated.

# **Audio (Option AUD)**

The audio software option enables display of the levels and phase of embedded audio, and drives the headphones output.

#### **Audio Processing**

The display FPGA extracts embedded audio data from the selected SDI data stream and sends it to the headphones output D/A converter on the CPU board. The FPGA also calculates the peak values for the selected meter ballistics (response characteristics).

The audio data has two paths to the display. On one path, peak values are read by the control processor, which then plots the bar and surround displays. On the second path, raw data samples are sent to the waveform processing engine, which interpolates and plots it to generate the lissajous, or "phase," display.

## **Fan Control**

There are multiple temperature sensors in different locations in the instrument. The control processor reads the temperature sensors and sets a target speed for the fans. The fan circuit holds the fan speed at the target by measuring the fan tachometer output, allowing reliable operation at low speed. If a fan is not turning, the circuit senses the stall and turns on a red LED (DS2 or DS3 on the CPU board). The fans are tested at power on. If a fan fails, a message is shown on screen and also entered into the diagnostic log.

# **Power Supply and Distribution**

External power may be supplied by either the provided power module or a customer-supplied 11-17 V DC power source. Protection circuits include a self-resetting fuse, transient filtering, and limiting, over- and under-voltage protection and current limiting. A latching relay controls standby mode. The nominal 12 V DC input powers 5 V and 3.3 V supplies. All three voltages are distributed to the CPU and FPGA boards to power circuits as well as lower voltage local regulators.

# **General Maintenance**

This section contains the information needed to perform periodic and corrective maintenance on the instrument. The following subsections are included:

- *Preventing ESD* General information on preventing damage by electrostatic discharge.
- *Inspection and Cleaning* Information and procedures for inspecting and cleaning the instrument.
- *Troubleshooting* Information for isolating and troubleshooting failed modules. Included are instructions for operating the diagnostic routines and troubleshooting trees. Most of the trees make use of the internal diagnostic routines to speed fault isolation to a module.
- Removal and Replacement Procedures Information and procedures for removing and replacing modules in the instrument.
- Repackaging Instructions Information on returning an instrument for service.

# **Preventing ESD**

Before servicing this product, read the *Safety Summary* and *Introduction* at the front of the manual, and the ESD information below.



**CAUTION.** Static discharge can damage any semiconductor component in the instrument.

When performing any service that requires internal access to the instrument, adhere to the following precautions to avoid damaging internal modules and their components due to electrostatic discharge (ESD).

- 1. Minimize handling of static-sensitive circuit boards and components.
- 2. Transport and store static-sensitive modules in their static protected containers or on a metal rail. Label any package that contains static-sensitive boards.
- **3.** Discharge the static voltage from your body by wearing a grounded antistatic wrist strap while handling these modules. Service static-sensitive modules only at a static-free work station.
- **4.** Nothing capable of generating or holding a static charge should be allowed on the work station surface.
- **5.** Handle circuit boards by the edges when possible.

- **6.** Do not slide the circuit boards over any surface.
- 7. Avoid handling circuit boards in areas that have a floor or work-surface covering capable of generating a static charge.

## **Inspection and Cleaning**

*Inspection and Cleaning* describes how to inspect for dirt and damage. It also describes how to clean the exterior and interior of the instrument. Inspection and cleaning are done as preventive maintenance. Preventive maintenance, when done regularly, may prevent malfunction and enhance reliability.

Preventive maintenance consists of visually inspecting and cleaning the instrument and using general care when operating it.

How often maintenance should be performed depends on the severity of the environment in which the instrument is used. A proper time to perform preventive maintenance is just before any instrument adjustment.

#### **General Care**

The cabinet helps keep dust out and should normally be in place during operation.



**WARNING.** To prevent injury or death, power off the instrument and disconnect it from line voltage before performing any procedure that follows.

#### Interior Cleaning

Use a dry, low-velocity stream of air to clean the interior of the chassis. Use a soft-bristle, non-static-producing brush for cleaning around components. If you must use a liquid for minor interior cleaning, use a 75% isopropyl alcohol solution and rinse with deionized water.

#### **Exterior Cleaning**

Clean the exterior surfaces of the chassis with a dry lint-free cloth or a soft-bristle brush. If any dirt remains, use a cloth or swab dipped in a 75% isopropyl alcohol solution. Use a swab to clean narrow spaces around controls and connectors. Do not use abrasive compounds on any part of the instrument that may damaged by it.



**CAUTION.** Avoid the use of chemical cleaning agents that might damage the plastics used in the instrument. Use only deionized water when cleaning the front-panel buttons. Use a glass cleaner to clean the LCD. For the rest of the instrument, use a 75% isopropyl alcohol solution as a cleaner and rinse with deionized water. Before using any other type of cleaner, consult your Tektronix Service Center or representative.

**Inspection – Exterior.** Inspect the outside of the instrument for damage, wear, and missing parts, using the following table as a guide. Immediately repair defects that could cause personal injury or lead to further damage to the instrument.

**Table 1: External inspection checklist** 

Item	Inspect for	Repair action
Cabinet, front panel, and cover	Cracks, scratches, deformations, damaged hardware	Repair or replace defective module
Front-panel knobs	Missing, damaged, or loose knobs	Repair or replace missing or defective knobs
Connectors	Broken shells, cracked insulation, and deformed contacts. Dirt in connectors	Repair or replace defective modules. Clear or wash out dirt
Carrying handle and cabinet feet	Correct operation	Repair or replace defective part
Accessories	Missing items or parts of items, bent pins, broken or frayed cables, and damaged connectors	Repair or replace damaged or missing items, frayed cables, and defective modules
LCD	Cracks	Replace the LCD assembly
	Dirty	Clean with glass cleaner

**Inspection – Interior.** To access the inside of the instrument for inspection and cleaning, you will need to remove the top cover.

Inspect the internal portions of the instrument for damage and wear, using Table 4-2 as a guide. Defects found should be repaired immediately.

If any circuit board is repaired or replaced, see if it is necessary to adjust the instrument. (See Table 2 on page 11.)



**CAUTION.** To prevent damage from electrical arcing, make sure that circuit boards and components are dry before applying power to the instrument.

Table 2: Internal inspection checklist

Item	Inspect for	Repair action
Circuit boards	Loose, broken, or corroded solder connections. Burned circuit boards. Burned, broken, or cracked circuit-run plating.	Remove and replace damaged circuit board.
Resistors	Burned, cracked, broken, blistered condition.	Remove and replace damaged circuit board.

Table 2: Internal inspection checklist (cont.)

Item	Inspect for	Repair action
Solder connections	Cold solder or rosin joints.	Resolder joint and clean with isopropyl alcohol.
Capacitors	Damaged or leaking cases. Corroded solder on leads or terminals.	Remove and replace damaged circuit board.
Wiring and cables	Loose plugs or connectors. Burned, broken, or frayed wiring.	Firmly seat connectors. Repair or replace modules with defective wires or cables.
Chassis	Dents, deformations, and damaged hardware.	Straighten, repair, or replace defective hardware.

**Cleaning Procedure – Interior.** To clean the instrument interior, perform the following steps:

- 1. Blow off dust with dry, low-pressure, deionized air (approximately 9 psi).
- 2. Remove any remaining dust with a lint-free cloth dampened in isopropyl alcohol (75% solution) and rinse with warm deionized water. (A cotton-tipped applicator is useful for cleaning in narrow spaces and on circuit boards.)

**STOP.** *If, after doing steps* 1 *and* 2*, a module is clean upon inspection, skip the remaining steps.* 

- **3.** If steps 1 and 2 do not remove all the dust or dirt, the instrument may be spray washed using a solution of 75% isopropyl alcohol by doing steps 4 through 6.
- **4.** Gain access to the parts to be cleaned by removing easily accessible shields and panels.
- **5.** Spray wash dirty parts with the isopropyl alcohol and wait 60 seconds for the majority of the alcohol to evaporate.
- **6.** Dry all parts with low-pressure, deionized air.

**Lubrication.** There is no periodic lubrication required for the instrument.

# **Troubleshooting**

The procedures in this section will help you trace the root cause of a problem back to one of the replaceable modules. In general, this is a board-level replacement but there are a few components on some boards that are replaceable.



**WARNING.** Before performing this or any other procedure in this manual, read the General Safety Summary and Service Safety Summary found at the beginning of this manual.

To prevent possible injury to service personnel or damage to electrical component, refer on how to prevent ESD. (See page 9.).

# **Getting Started**

This procedure consists of two main sections: the first section contains the *Symptoms and Causes* table, and the second section contains a set of *Detailed Troubleshooting Procedures*. The table lists common problems and should help you identify the problem or it may direct you to one of the detailed troubleshooting procedures in the second section. You should investigate and resolve the first symptom found, as the Symptoms and Causes table assumes that the functions covered earlier in the table are working correctly. If you do not find your instrument's problem in the table, or if no specific problem was reported by the user, then follow the steps in the *Unknown Problem* section in the Symptoms and Causes table.

The WFM5200 Waveform Monitor is highly configurable, and its behavior is sometimes complex. Before troubleshooting in-depth, verify that:

- The installed options are as expected. See CONFIG > Utilities > View Instrument Options
- The current settings support the expected behavior. A good first step is to recall the Factory Presets. To do this, press PRESET > Recall Preset > Recall Factory Preset.

To fully test this instrument, you must have an appropriate Serial Digital Video source. In some cases, you may also need receivers or an oscilloscope to check outputs.

This instrument consists of several boards and major components. The objective of this troubleshooting guide is to isolate a problem to a module or board so it can be replaced. This guide does not provide information to troubleshoot to the component level.

Standard boards and modules:

- Power Supply (external)
- Display Assembly (LCD, front panel board with buttons, LEDs, and knobs)
- FPGA board
- CPU board
- SDI board
- External Reference I/O board

**Table 3: Required test equipment** 

Test equipment	Requirements	Example
SDI serial digital video test generator with	1080p 59.94 3 Gb/s signals required:	Tektronix TG700 with an HD3G7 module
embedded audio. Instruments with option 3G require a 3 Gb/s SDI source.	■ 100% color bars	(Embedded audio needed for audio options)
	<ul><li>SDI Matrix Split Field Pathological Signal</li></ul>	
	1080i 59.94 HD signals required:	Tektronix TG700 with HDVG7 module
	■ 100% color bars	(Embedded audio needed for audio options)
	■ 10 bit shallow ramp	
	<ul><li>SDI Matrix Split Field Pathological Signal</li></ul>	
	■ 100% sweep	
	525/270 SD signals required:	Tektronix TG700 with DVG7 module
	■ 100% color bars	(Embedded audio needed for audio options)
	■ 10 bit shallow ramp	
	■ SDI Matrix Pathological Signal	
	■ 100% sweep	
XGA Monitor	Computer monitor capable of 1024 x 768 x 60 Hz scan rate	
Voltmeter		Fluke 87 or equivalent
Oscilloscope	Video trigger capability	Tektronix TDS3000C Series, Tektronix DPO70404

Table 4: Symptoms and causes

Symptom	Possible cause or detailed troubleshooting procedure to follow
No LEDs lit and no internal or external display	Perform General Checks
	Perform Power Switch Checks
	Perform Basic Power Supply checks
Some LEDs lit, but no external	Perform General Checks
display and no internal display	Verify external monitor functionality with another XVGA source
	Perform Basic Power Supply Fault Checks
	Perform CPU Boot Checks
Internal display functions normally	Verify external monitor functionality with another XVGA source
but external display does not function normally	Replace FPGA board
External display functions normally but internal does not	Perform LCD Troubleshooting
The display functions normally but	Check front panel cable
the front panel buttons are all dark or inoperative	Replace front panel assembly
Power Up Diagnostic failures:	
Faults referring to Main or CPU board	Replace CPU board
Faults referring to FPGA functions	Replace FPGA board
Fan faults	Perform Fan Checks
Advanced Diagnostics failures:	Replace FPGA board
Functional or Performance	Perform Power Up Diagnostics
Verification Test Failures:	Perform Advanced Diagnostics
	Perform Diagnostic Monitor Voltage Checks
Use the table below to isolate the faulty module based on problem area:	
SDI in, one channel bad	Replace SDI board
SDI in, all four channels bad	Replace FPGA board
Waveform or graphic displays corrupted	Replace FPGA board
SDI OUT	Replace FPGA board
Audio bars bad	Replace FPGA board
USB bad	Replace CPU board
Ethernet bad	Replace CPU board
Fans bad	Perform Fan checks
Headphones bad, audio bars ok	Replace CPU board

Table 4: Symptoms and causes (cont.)

Symptom	Possible cause or detailed troubleshooting procedure to follow
Reference or LTC waveform bad	Check Reference I/O cable
	Replace Reference I/O board
Ground closure input or Alarm output bad	Check Reference I/O cable
	Replace Reference I/O board
Unknown Problems An instrument may come into service with vague or intermittent symptoms. In a case like this, the following set of tests may help find the problem or the marginal condition.	1. Check the diagnostic log. This log records a variety of problems and will enable you to see
	messages for an error that may not be currently happening.  2. Check the power supplies by performing the Diagnostic Monitor Voltage Checks. A marginal supply can lead to intermittent operation if it is near the acceptable threshold. This includes the external power source and the secondary supplies on each board.
	<ol><li>Perform the incoming inspection tests. This will exercise a majority of the functions in the unit and includes the Advanced Diagnostics. Some parts of the test may not be necessary for all problem areas.</li></ol>

## **Detailed Troubleshooting Procedures**

The following tests should be run as indicated in the *Symptom and Causes* table. (See Table 4 on page 15.). The procedures check for specific problems or will help you isolate a problem to a board. You can run them at any time for informational purposes, but if you do not run the procedures in the correct context, then the final recommendation identifying a root cause might be suspect.

#### **General Checks**

- 1. Verify that the external power is connected, stable and between 10 and 19 Vdc.
- 2. Check that all internal cables are correctly connected and seated.
- **3.** Check for any discolored or burned components.

#### **Power Switch Checks**

This procedure requires partial disassembly and should only be performed if the unit fails to show any indication of operation. This procedure may also be used to troubleshoot a unit that cannot be powered off from the front panel power button.

Remove the Reference I/O and FPGA boards to gain access to the SDI board test points. Connect power and measure the voltage at power connector J7 pin 4 with respect to chassis ground. The external power supply voltage (10 to 19 Vdc) should be present at this pin.

If no LEDs are lit on the front panel or CPU board, press the front panel power button to check that the initial problem is still present. If there is still no indication of power up, press button S1 on the SDI board. If S1 also has no effect, replace the SDI board.

If S1 causes normal power up (indicated by lit red and green LEDs on the CPU board), then the problem is in the connection from the front panel button to the SDI board. Disconnect power, disassemble as necessary, and check for continuity or low resistance of the following links:

- Button resistance: On the front panel board, resistance from J1 pin 2 to ground should be less than 1000 ohms when the power button is pressed, greater than 20k ohms when released.
- Front panel cable continuity: Resistance from Front Panel board J1 pin 2 to CPU board J1 pin 2 should be less than 10 ohms.
- CPU board continuity: Resistance from J1 pin 2 to J2 pin 211 should be less than 10 ohms.
- SDI board continuity: Resistance from J2 pin 211 to switch S1 pins nearest the edge of the board should be less than 10 ohms.

Replace any cable or board that fails the resistance checks.

# Basic Power Supply Checks

This section describes methods for verifying the proper operation of the basic power supplies on the SDI board. This procedure requires partial disassembly, and should only be performed if the unit fails to produce evidence of CPU boot up.



**WARNING.** Internal power supplies are all low voltage so no safety shield is present.

This instrument requires an external DC power source capable of providing 11 to 17 Vdc at 3A. The provided AC adapter accepts 90 to 264 VAC and outputs around 12 VDC with 4 A capability. This voltage passes through a power switch circuit on the SDI board, and is present at the "+12V" test point if instrument power is on.

The switched +12V powers +5V and +3.3V switching power supplies, also located on the SDI board. These three voltages are the basic power supplies distributed to the rest of the instrument.

Remove the Reference I/O and FPGA boards to gain access to the SDI board power test points. Locate the +12V, +5V and +3.3V test points on the SDI board. (See Figure 2.) Measure the voltages with a DVM and check against the allowable ranges. (See Table 5.) If the voltages are outside of the allowed range, replace the SDI board. If voltages are within the allowed range, replace the CPU board.

Table 5: SDI board basic supplies

Nominal (+V)	Allowed range (+V)
+12V	11 to 17
+5V	4.85 to 5.15
+3.3V	3.2 to 3.4

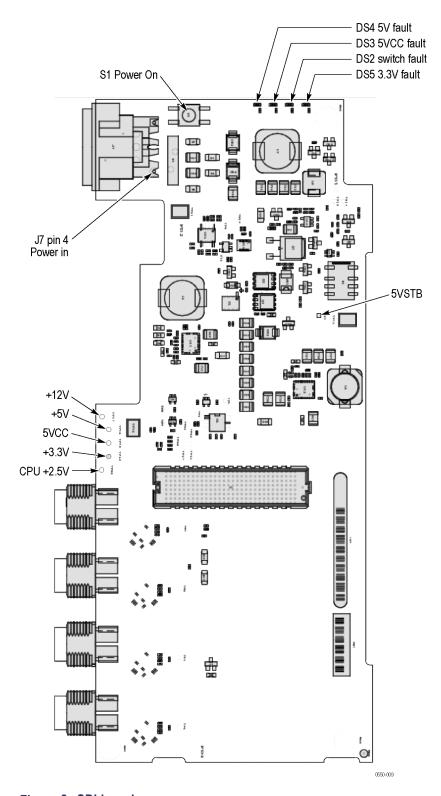


Figure 2: SDI board

# Basic Power Supply Fault Checks

This procedure requires disassembly. It should be performed only if the unit fails to operate to the point where diagnostics can be run, and if the power button is continuously lit red. The power button is normally red for about 2 seconds when the unit is first powered up. In addition, the power button may be red in the case of any detected hardware fault. To isolate the symptom to a power supply fault, it is necessary to view the fault LEDs on the SDI board.

Remove the carrying case if present to gain viewing access to the SDI board fault LEDs DS2, DS3, DS4 and DS5, located on the right edge of the SDI board. These are visible through the lower right side ventilation holes. Connect power and press and hold the power button. If none of the four fault LEDs is red, then exit this procedure.

LEDs DS1, and DS3 indicate faults on the SDI board. If any one of them is red, replace the SDI board. If either DS4 or DS5 is lit, then isolate the faulty assembly by removing them one at a time in the order listed below. Disconnect the power before removing each assembly and then reconnect power and press the power button to test. The first board or cable to be removed which causes an SDI board fault LED to stop lighting is probably faulty and should be replaced.

- 1. Reference I/O cable at FPGA board J4
- 2. LCD cable at FPGA board J7
- 3. FPGA board
- **4.** Display backlight cable at CPU board J5 (remove SDI board to gain access, then reinstall SDI board)

For the next two steps, test by pressing SDI board switch S1 instead of the (disconnected) front panel power button:

- 5. Front panel cable at CPU board J1 (remove SDI board to gain access, then reinstall SDI board)
- **6.** CPU board (remove SDI board from CPU and test SDI board in isolation)

If any SDI board fault LED DS1 through DS5 is red when the board is tested in isolation, replace the SDI board.

#### **CPU Boot Checks**

The objective of this test is to determine whether CPU+FP+SDI is booting correctly, in which case the missing external display is an FPGA board fault. If CPU+FP+SDI is not booting to completion, the Basic Power Supply Fault Checks decide whether the SDI or CPU+FP is at fault. The primary indicator is the front panel behavior, which is presumed good based on single-fault assumption. Since a good unit boots completely with the front panel disconnected, an initial and final test are done to the front panel to guarantee that the front panel is not hanging boot.

This procedure requires disassembly, and should be performed only if some front panel buttons light, but neither the external nor internal display are functional.

Observe the sequence of front panel button illumination at power on. Normal power up sequence has the following appearance. Time "T" is in seconds.

T=0 : press power button to power up

GAIN, SWEEP, MAG buttons light

Initial button lighting sequence starts with <,^,>,V buttons on for about ½ second each

T=3: All buttons flash for fraction of a second, then all go out out. The button sequence changes to 1A, 1B, ... counterclockwise around the display

T=10 to 20: Power button may turn red.

T=20: Button sequence stops.

T= 28: Brief changes, then all buttons dim (per backlight setting).

T= 32: Previous power down state is restored to buttons. Usually two or three become bright.

If the power up behavior is similar to that described, then the CPU is booting correctly, and the display fault is likely to be on the FPGA board. Replace the FPGA board.

If the power up behavior differs from that described above, then perform the Basic Power Supply Fault Checks to further isolate the faulty module.

#### LCD Troubleshooting

Perform this test if there is no display on the internal LCD, but an external monitor connected to the DVI output displays the usual instrument display starting with Power-up Diagnostics.

- 1. Check the cable from the internal display to J7 on the FPGA board. This carries the XGA data to the display.
- 2. Check to see if the backlight is on. Look into the vent holes behind the upper right corner of the LCD. You should see the backlight come on about 20 seconds after power up.
- **3.** If the backlight is on, replace the front panel assembly.
- **4.** If the backlight is not on, check the backlight power cable from the LCD assembly to the CPU board J5. Also check connector J18 itself for any solder issues.
- **5.** If the backlight is still bad, replace the front panel assembly (although there is still a small chance the problem is in the main board).

### **Fan Checks**

This instrument contains two fans: they are controlled by both hardware and software. Hardware controls the fans to a certain speed, but software sets the speed target as a function of the temperature measured on a variety of temperature sensors.

If a fan fails, its corresponding LED lights up on the CPU board:

Fan 1 fails: LED DS3 lightsFan 2 fails: LED DS2 lights

A fan failure is sensed through tachometer feedback; a fault will be asserted if the fan is not connected, is stalled, or if the tachometer feedback line is not working correctly.

If one fan fails, the control circuit will increase the voltage to the 13.5 V max level, causing the remaining fan to run at maximum speed.

The normal voltage to drive the fans (pin 1) varies from about 6 V to 13.5 V depending on internal temperature.

If a fan is not spinning, measure the voltage on pin 1 of the connector on that fan. If the voltage is near 13 V, then replace the fan. If the voltage is not above 10 V, then replace the CPU board.

If both fans are spinning, but either LED DS2 or DS3 is lit, the problem is probably the tachometer feedback line on pin 3 of either fan. Inspect the wiring and resistors R201, R203, R202, and R204 on the CPU board, and use the oscilloscope to look for a 3.3 V square wave on the tachometer feedback line. If resistors are intact but there is no signal on the tachometer line, replace the affected fan.

### **Power-Up Diagnostics**

To examine the Power-up Diagnostics results, press the **CONFIG** button, then select **Utilities** > **View Diagnostic Log**.

Each power on is indicated by a boot time stamp, followed by a list of power on tests. If any failures are indicted then refer to the action as noted above.

### **Advanced Diagnostics**

To run the Advanced Diagnostics, press the **CONFIG** button, then select **Utilities** > **Run Advanced Diags**.

Advanced Diagnostics includes tests that check the interfaces between FPGAs and memory on the FPGA board. If any of these tests fails, replace the FPGA board.

### Diagnostic Monitor Voltage Checks

This test uses the built-in voltage monitor to check many power supplies on the SDI, FPGA and CPU boards. It requires successful boot up, display and front panel operation:

- 1. Press and hold OTHER, then select Diag Monitor to display the diagnostic monitor screen.
- 2. Navigate to pages 2 and 3 to display the power supply voltages. If the "Last" value of any voltage is outside the allowable range, it will be displayed in red. Voltage values are updated about every 10 seconds.
- **3.** If any voltage is out of range, replace the faulty module as indicated by the first word of the displayed line. "Input" indicates the power supply is on the SDI board.

## Front Panel Button Troubleshooting

Perform this test if the power supplies are good, but none of the buttons are lit or respond to presses:

- 1. Cycle the power to the unit. Immediately after power on, three buttons (GAIN, SWEEP, and MAG) should be lit continuously and the other buttons should be lit one at a time in a walking pattern.
- **2.** If the buttons are not lit, check the 10 pin cable from the keypad to the main board J21. If the cable is connected and good, then replace the front panel assembly.

## **Removal and Replacement Procedures**

This section contains information about removal and replacement of all modules in the waveform monitor.

### **Preparation**



**WARNING.** Before doing this or any other procedure in this manual, read the safety summaries found at the beginning of this manual. Also, to prevent possible injury to service personnel or damage to the instrument components, read Installation in Section 2, and Preventing ESD in this section.

This subsection contains the following items:

- This preparatory information that you need to properly do the procedures that follow.
- List of tools required to remove and disassemble all modules.
- Procedures for removal and reinstallation of the modules.



**WARNING.** Before doing any procedure in this subsection, disconnect the power cord from the line voltage source. Failure to do so could cause serious injury or death.

**NOTE.** Read Equipment Required for a list of the tools needed to remove and install modules in this instrument. (See Table 6 on page 24.) Read the cleaning procedure before disassembling the instrument for cleaning.

**Equipment Required.** Most modules in the instrument can be removed with a screwdriver handle mounted with a size T-10, Torx screwdriver tip. All equipment required to remove and reinstall the modules is listed in the following table.

Table 6: Tools required for module removal

Item no.	Name	Description	General Tool number
1	Screwdriver handle	Accepts TORX-driver bits	620-440
2	T8 TORX tip	Used to remove screws securing XLR power connector to rear panel.	Standard tool
3	T10 TORX tip	Used for removing most instrument screws. Torx-driver bit for T10 size screw heads	640-235
4	T15 TORX tip	Used for removing instrument screws. Torx-driver bit for T15 size screw heads	640-247
5	1/8 inch flat-bladed screwdriver	Screwdriver for unlocking cable connectors	Standard tool
6	Angle-Tip Tweezers	Used to remove front panel knobs	Standard tool
7	3/ <sub>16</sub> inch nut driver	Used to remove jack screws and front panel spacer posts	Standard tool
8	5/ <sub>16</sub> inch nut driver	Used to remove nut on AC ground lug	Standard tool
9	MA-800G Soldering Aid (spudger)	Used to remove the front panel trim	Standard tool
10	Soldering iron (15 W)	Used for replacing Main board fuses	Standard tool
11	Long nose pliers	Used to compress connector lock tabs	Standard tool

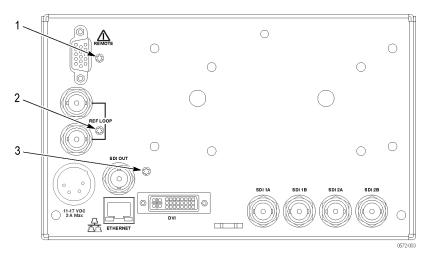
### **Module Removal**

The removal of most of the modules is a straightforward process, and can be determined by a quick study of the exploded diagram in the *Replaceable Parts List*. (See Figure 8.) The boards need to be removed in the order listed here.

### Top cover

The top cover is a complete enclosure design. Follow these steps to remove the top cover:

- 1. Place the instrument face-down on a surface that will not mar the front panel. A thin piece of anti-static foam works nicely.
- 2. Remove the three pan-head 32 X 0.250 T15 screws from the back of the instrument. When reinstalling, tighten these to 0.9 N-M (8 in/lb).



- **3.** Remove the nine flat-head 32 X 0.250 T10 screws on the front edge of the top cover (three on the top, and two on each side and the bottom). When reinstalling, tighten these to 0.9 N-M (8 in/lb).
- **4.** Slide the top cover up off the Waveform Monitor. When reinstalling, make sure to push the cable on the left side into the chassis as you slide the top cover onto the Waveform Monitor.

# Rear panel/Reference I/O Board

The rear panel is a one-piece design, with two short sides which slide into the main chassis. Follow these steps to remove the rear panel:

- 1. Remove the two pan-head 3 2 X 0.250 T15 screws that attach the rear panel to the fan bracket. When reinstalling, tighten these to 0.9 N-M (8 in/lb).
- 2. Remove the  $9/_{16}$ " nuts and their lock washers from the seven BNC connectors. When reinstalling tighten the nuts to 1.58 N-M (14 in/lb).
- 3. Remove the two  $\frac{3}{16}$ " jack screws from the DVI connector. When reinstalling, tighten these to 0.45 N-M (4 in/lb).

- **4.** Remove the two 40 X 0.375 T8 flat-head screws that secure the XLR connector to the rear panel. When reinstalling, tighten these to 0.62 N-M (5.5 in/lb).
- 5. Remove the four 32 X 0.250 T10 flat-head screws that attach the rear panel to the sides of the main chassis, two on each side. When reinstalling, tighten these to 0.9 N-M (8 in/lb).
- **6.** Pull the sides of the main chassis out slightly, to disengage the alignment tabs from the slots in the rear panel. Then move the rear panel, with the Reference I/O board still attached, slightly away from the main chassis. When reassembling, slightly push out the sides of the main chassis until the alignment tabs engage the slots in the rear panel.
- 7. Disconnect the cable that connects the Reference I/O board at J7 with the FPGA board. Then set the rear panel, with Reference I/O board attached, on the static-free work surface.



**CAUTION.** Use care when removing the cable attached to J7 on the Reference I/O board. If you let the connector tip to the side while disconnecting the cable you may bend some of the pins on the board. Pull the connector straight away from the board when removing the cable to avoid bending pins.

**Reference I/O board/rear panel.** This procedure is only necessary if you are replacing the Reference I/O board:

- 1. On the rear panel, remove the two  $^{3}/_{16}$ " jack screws that attach the Ground Closure Interface connector to the Reference I/O board. When reinstalling, tighten these to 0.45 N-M (4 in/lb).
- **2.** Separate the Reference I/O board from the rear panel.
- 3. Place the I/O board on the static-free work surface.

#### Fan bracket/Main Chassis

- 1. Remove the two pan-head 32 X 0.250 T15 screws that attach the fan bracket to the main chassis. When reassembling, tighten these to 0.9 N-M (8 in/lb).
  - When reinstalling the fan bracket, make sure not to pinch any cables between the fan bracket and the main chassis. (See Figure 3.)
- 2. Carefully lift the fan bracket and fans out of the main chassis. Note the way the fan cables are wound around the fans, then unwind them and drape the fan bracket over the side of the main chassis (in order to get them out of the way of removing the boards below).
- **3.** Continue disassembling the instrument. You first must remove the FPGA board and the SDI board in order to access the fan drive connectors, which are located below these boards on the CPU board.

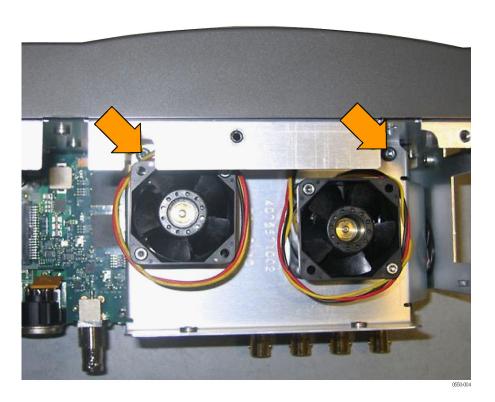


Figure 3: Screws that attach fan bracket to main chassis

## FPGA board

1. Remove the three pan-head 40 X 0.187 T10 screws that secure the FPGA board to the SDI board below it. When reassembling, tighten these screws to 0.62 N-M (5.5 in/lb).

When reinstalling the FPGA board, flex the board slightly to ensure that none of the cables are pinched between the board and the main chassis.

- 2. Lift the FPGA board straight up, in order to disconnect the inter-board connector on the bottom of the FPGA board from the SDI board. When reinstalling, make sure that these connectors are aligned correctly before pushing the FPGA board down onto the SDI board.
- **3.** Disconnect the Display cable from J7 on the FPGA board. Pull the plug straight away from the connector, to prevent damage.
- **4.** Place the FPGA board on a static-free work surface.

#### SDI board

- 1. Remove the three  $\frac{3}{16}$  inch spacer posts that secure the SDI board. When reassembling, tighten these to 6.2 N-M (5.5 in/lb).
  - When reinstalling the SDI board, flex the board slightly to ensure that none of the cables are pinched between the board and the main chassis.
- 2. Lift the SDI board straight up, to disconnect the inter-board connector on the bottom of the SDI board from the CPU board. When reinstalling, make sure that these connectors are aligned correctly before pushing the SDI board down onto the CPU board.
- **3.** Place the SDI board on a static-free work surface.

### Fan/Bracket Disassembly

- 1. Disconnect the fan cables from J7 and J8 on the CPU board. These connectors are locked in place: push the release tab, in the middle, to unlatch them. When reinstalling, attach the fan cables before seating the CPU board on the main chassis; make sure to push the fan cable plugs into the connectors until they snap into place. Then, seat the CPU board into the main chassis and drape the fan bracket and cables over the right side of the front panel to keep them out of the way. (You'll need to reinstall the SDI and FPGA boards before reinstalling the fan bracket.)
- 2. Separate the fan bracket from the main chassis by pulling the cables out through the slots.
- **3.** Remove the two pan-head 40 X 1.500 T10 screws from the front of each fan.
- **4.** When reassembling, place the fans so that the labels are facing the fan bracket. Insert the screws in the holes noted in the figure below.

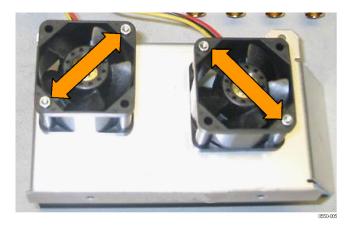


Figure 4: Fan screw placement

### **CPU** board

- 1. Using a  $^{3}/_{16}$ " nut driver, remove the three .276 L spacer posts that secure the CPU board to the chassis. When reinstalling, tighten these to 0.62 N-M (5.5 in/lb).
- 2. Remove the one pan-head 40 X 0.187 T10 screw that secures the CPU board to the main chassis. When reinstalling, put the screw in the lower left hand corner of the board. Tighten this screw to 0.62 N-M (5.5 in/lb). (See Figure 5.)
- **3.** Disconnect the front panel cable from J1 on the CPU board. Then disconnect the backlight cable from J5 on the CPU board. Pull these plugs straight away from their connectors, to prevent damage.
- **4.** Move the CPU board away from the main chassis and place it on the static-free work surface.



Figure 5: CPU board screw and spacer posts

# Front Panel/Bezel Disassembly

- 1. Remove the two flat-head 40 X 0.25 T10 screws that attach the main chassis to the LCD module. When reassembling, tighten these screws to 0.45 N-M (4.0 in/lb).
- **2.** Use a Phillips screwdriver to remove the two 40 X 0.187 P1 screws that secure the bottom of the bezel to the main chassis. When reassembling, tighten these screws to 0.62 N-M (5.5 in/lbs).
- **3.** Pull the bezel forward. Slide the cable out of the slot on the main chassis. When reassembling, pull the cable that connects to the front panel through the slot on the main chassis first, then reattach screws.

**Remove the front panel board from the bezel.** The front panel board can be removed from the bezel and replaced, if needed:

- 1. Disconnect the front panel cable from J1 on the front panel board.
- **2.** Remove the three knobs on the front panel.
- 3. Remove the one pan-head 40 X 0.187 T-10 screw that secures the front panel to the bezel, and one spring-clip. When reassembling, be sure to position the spring-clip so that it angles above R42. (See Figure 6.)
- **4.** Use a  $^{3}/_{16}$  inch nutdriver to remove the two 0.687L 0.188 hex spacer posts that secure the front panel board to the bezel.
- **5.** Lift the front panel board away from the bezel.
- **6.** Remove the elastomer mat from the bezel.

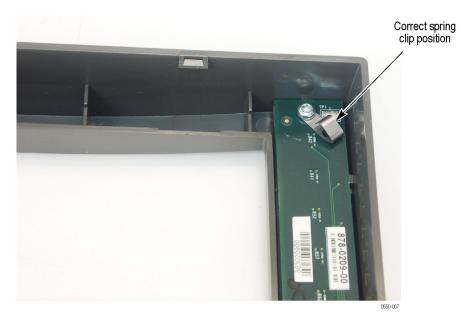


Figure 6: Correct spring clip position

### **LCD Module**

- 1. Remove the 6 pan-head 40 X 0.187 T-10 screws that attach the LCD module to the main chassis. (Push aside the Poron foam gasket to reach the screws.) (See Figure 7.)
- **2.** Carefully lift up the LCD module, pulling the LCD and backlight cables up through the slots on the main chassis.
- **3.** The LCD module should not be further disassembled. The entire module, including the LCD, board and cables, can be replaced by ordering part number 119–7439–01.

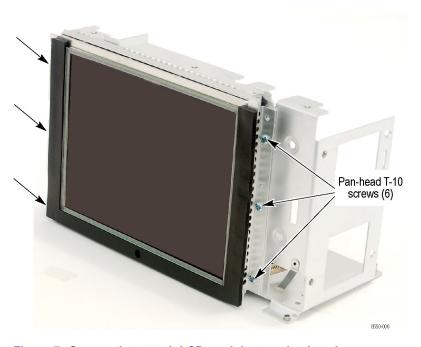


Figure 7: Screws that attach LCD module to main chassis

# **Repackaging Instructions**

This section contains the information needed to repackage the instrument for shipment or storage.

## **Packaging**

When repacking the instrument for shipment, use the original packaging. If the packaging is unavailable or unfit for use, contact your local Tektronix representative to obtain new packaging. Refer to *Contacting Tektronix* on the back of the Title page for the mailing address, the email address, and phone number.

Seal the shipping carton with an industrial stapler or strapping tape.

## **Shipping to the Service Center**

Contact the Service Center to get an RMA (Return Material Authorization) number, and any return or shipping information you may need.

If the instrument is being shipped to a Tektronix Service Center, enclose the following information:

- The RMA number.
- The owner's address.
- Name and phone number of a contact person.
- Type and serial number of the instrument.
- Reason for returning.
- A complete description of the service required.

Mark the address of the Tektronix Service Center and the return address on the shipping carton in two prominent locations.

# **Replaceable Parts**

This section contains a list of the replaceable modules for your instrument. Use this list to identify and order replacement parts. Note that not all parts listed in this section are present on every model. The parts present will depend on the model and options installed.

### **Parts Ordering Information**

Replacement parts are available through your local Tektronix field office or representative.

Changes to Tektronix products are sometimes made to accommodate improved components as they become available, and to give you the benefit of the latest improvements. Therefore, when ordering parts, it is important to include the following information in your order:

- Part number
- Instrument type or model number
- Instrument serial number
- Instrument modification number, if applicable

If you order a part that has been replaced with a different or improved part, your local Tektronix field office or representative will contact you concerning any change in part number.

### **Module Servicing**

Modules can be serviced by selecting one of the following three options. Contact your local Tektronix service center or representative for repair assistance.

**Module Exchange.** In some cases, you may exchange your module for a remanufactured module. These modules cost significantly less than new modules and meet the same factory specifications. For more information about the module exchange program, call 1-800-833-9200. Outside North America, contact a Tektronix sales office or distributor; see the Tektronix Web site for a list of offices: www.tektronix.com.

**Module Repair and Return.** You may ship your module to us for repair, after which we will return it to you.

**New Modules.** You may purchase replacement modules in the same way as other replacement parts.

## **Using the Replaceable Parts Lists**

This section contains lists of the mechanical and/or electrical components that are replaceable for your instrument. Use this list to identify and order replacement parts. The following table describes each column in the parts list.

### Parts list column descriptions

Column	Column name	Description
1	Figure & index number	Items in this section are referenced by figure and index numbers to the illustrations that follow.  Orderable modules show the figure number without an index number.
2	Tektronix part number	Use this part number when ordering replacement parts from Tektronix.
3 and 4	Serial number	Column three indicates the serial number at which the part was first effective. Column four indicates the serial number at which the part was discontinued. No entry indicates the part is good for all serial numbers.
5	Qty	This indicates the quantity of parts used.
6	Name & description	An item name is separated from the description by a colon (:). Because of space limitations, an item name may sometimes appear as incomplete. Use the U.S. Federal Catalog handbook H6-1 for further item name identification.

**Abbreviations** Abbreviations conform to American National Standard ANSI Y1.1-1972.

Table 7: Replaceable parts list

Fig. & index	Tektronix part	Serial no.	Serial no.	•	
number	number	effective	discont'd	Qty	Name & description
5-1					WFM5200 Exploded View
-1	119-7441-00			2	FAN ASSEMBLY; DC,12V;0.105A,8.6 CFM,30DBA,3 LEAD, TACH OUTPUT, WITH CONN & HOUSING, SAFETY CONTROLLED
-2	211-1161-00			4	SCREW,MACHINE; 4-40 X 1.500,PAN HEAD,T-10 TORX, ZINC PLATED STEEL
-3	407-5571-00			1	BRACKET FAN MOUNT
-4	211-0722-01			7	SCREW,MACHINE; 6-32 X 0.250,PNH,STL,CDPL,T-15 TORX DR
-5	200-5189-00			1	COVER, INTERNAL, EMI
-6	211-0734-00			13	SCREW,MACHINE; 6-32 X 0.250,FLH100,STEEL,ZINC FINISH,T-10 TORX DR
-7	333-4651-00			1	REAR PANEL (REAR I/O)
-8	210-1039-00			7	WASHER,LOCK; 0.521 ID,INT,0.025 THK, STEEL, ZINC FINISH
-9	220-0497-00			7	NUT,PLAIN,HEX; 0.5-28 X 0.562 HEX,BRS NI (NICKEL) PLATED
-10	878-6504-00			1	CIRCUIT BOARD SUBASSY;REF IO,UNTESTED, 389441200 ROHS COMPLIANT
-11	214-3903-00			4	VENDOR: LYNTRONSCREW, JACK; 4-40 X 0.312 LONG, 0.188 H HEX HEAD STAND OFF, 4-40 INT THD, X 0.312 THD EXT 4-40, STEEL, ZINC PLATED
-12	863-6501-01			1	CIRCUIT BOARD SUBASSY;FPGA, TESTED, 389440900
-13	174-5921-00			1	CABLE FPGA TO REF/IO 40 PIN
-14	214-4748-00			2	HEAT SINK,SEMIC; IC,PGA 11X11/MQUAD/27MM BGA;1.1 X 1.1 X 0.25 H,PIN FIN,AL,BLACK ANODIZE;658-25AB
-15	211-1117-00			13	SCREW, MACHINE; 4-40 X 0.187, PAN HEAD, STEEL, ZINC FINISH, T-10, TORX DR
-16	129-1713-00			6	SPACER POST; .276 L, 4-40 M/F .188 HEX
-17	863-6503-01			1	CIRCUIT BOARD SUBASSY;SDI,TESTED, 389441100
-18	211-0380-00			2	SCREW, MACHINE; 4-40 X 0.375, FLH, STEEL, ZINC FINISH, T8
-19	863-6502-01			1	CIRCUIT BOARD SUBASSY;CPU,TESTED, 389441000
-20	260-5015-00			1	SWITCH,PUSH; SPST,TACT;50MA,50V,MOMENTARY,SILVER CONTACTS
					(Reset button, on bottom of CPU board)
-21	146-0109-00			1	BATTERY,DRY; 3.0V,LITHIUM MANGANESE DIOXIDE,210MAH,20 X 3.22MM COIN CELL WITH SOLDER TABS,CR2032-1HF1; SAFETY CONTROLLED
-22	214-5305-00			1	SPRING, GROUND CLIP FRONT PHONE JACK, USB
-23	348-2003-00			1	BUMPER, RUBBER; CLEAR, 0.375 DIA X 0.200 H
-24	441-2644-00			1	CHASSIS, MAIN WFM
-25	119–7439–01			1	DISPLAY MODULE; LCD,COLOR;1024X768 (XGA), 6.5 DIAG,TFT,8/6-BIT LVDS,500 NIT BACK LIGHT,0.13 MM PIXEL PITCH,21MS, SIDE MOUNT, NL10276BC13
-26	214-5152-00			1	SPRING,CLIP
-27	174-5920-00			1	CABLE ASSEMBLY DISPLAY, 20 PIN
-28	174-5485-00			1	CABLE ASSEMBLY DISPLAY INVERTER; 15 PIN; LED BACKLIGHT TO DISPLAY
-29	337-4419-00			1	PORON FOAM SHIELD
-30	863-0209-00			1	CIRCUIT BD SUBASSY;389410200;FP;WFM5000, WFM4000,ROHS COMPLIA
-31	129-1636-00			2	SPACER POST: 4-40M/F,0.687L,SST,0.188HEX
-32	174-5492-00			1	CABLE ASSEMBLY, 10 PIN; FP TO MAIN; ROHS TO ROHS.
-33	260-2922-00			1	SWITCH KEYPAD (ELASTOMER MAT)
-34	426-2631-01			1	FRAME; FRONT BEZEL,PC/ABS,TV GRAY, SAFETY CONTROLLED

Table 7: Replaceable parts list (cont.)

Fig. & index number	Tektronix part number	Serial no. effective	Serial no. discont'd	Qty	Name & description
-35	335-2515-00			1	FRONT LEXAN WFM 5200
-36	335-2516-00			1	MARKER, IDENTIFICATION (ID LABEL, WFM5200)
-37	366-0859-01			3	ASSEMBLY, KNOB; .470 DIAMETER, SOFT TOUCH
-38	211-0119-00			2	SCREW, MACHINE; 4-40 X 0.25, FLH, 100 DEG, STEEL, BLACK ZINC, POZ
-39	337–4488–00			1	SHIELD, GLASS DISPLAY FRONT, FOR 6.5 IN, DOUBLE SIDED AR TREATMENT, WFM
-40	407–5443–00			1	BRACKET, CRADLE`

